【CLAIMS】

1. An electronic device comprising:

a housing including a front plate and a rear plate;

a non-conductive supporting member disposed in the housing to be adjacent to the rear plate, the supporting member including a first area, a second area spaced apart from the first area, and a third area connecting the first area and the second area;

a conductive pattern portion disposed over the first area of the supporting member and configured to generate a magnetic field;

a heat dissipation member disposed to at least partially overlap the conductive pattern portion; and

an antenna including a circuit board, a conductive portion disposed on one surface of the circuit board, and a ground portion disposed on the other surface of the circuit board,

wherein the conductive portion of the antenna is disposed over the second area, and

wherein the heat dissipation member extends from the first area to the third area, and the ground portion of the antenna extends from the second area to the third area to contact at least a portion of the heat dissipation member.

2. The electronic device of claim 1, wherein the heat dissipation member and the ground portion are integrally formed.

3. The electronic device of claim 1, further comprising:

a main circuit board disposed between the supporting member and the front plate, in the housing; and

an electric component disposed on the main circuit board and disposed to at least

partially overlap the second area of the supporting member.

4. The electronic device of claim 3, wherein the heat dissipation member and the ground portion provide a path through which heat generated from the electric component is diffused through the ground portion to the heat dissipation member.

5. The electronic device of claim 2, wherein the conductive portion of the antenna is a patch type and implements an ultra-wide band (UWB) antenna.

6. The electronic device of claim 1, further comprising a shielding member disposed between the conductive pattern portion and the heat dissipation member.

7. The electronic device of claim 6, wherein the heat dissipation member is flexible and includes a first heat dissipation portion disposed to face the shielding member and a second heat dissipation portion extending to the antenna, and

wherein the second heat dissipation portion includes a 2-1th heat dissipation portion extending from an end of the first heat dissipation portion and at least partially spaced apart from the third area of the supporting member and a 2-2th heat dissipation portion extending from the 2-1th heat dissipation portion and formed to overlap one area of the ground portion.

8. The electronic device of claim 7, further comprising a conductive adhesive disposed between the 2-2th heat dissipation portion of the heat dissipation member and the one area of the ground portion to adhere the 2-2th heat dissipation portion and the one area of the ground portion and to provide a heat transfer path.

9. The electronic device of claim 7, wherein the heat dissipation member includes at least one high-thermal conductance material, wherein the at least one high-thermal conductance material includes at least one of graphite, a carbon nanotube, a natural regenerated material, silicone, silicon, or a copper foil.

10. The electronic device of claim 1, wherein the conductive pattern portion includes a conductive pattern configured to generate a magnetic field and a base member disposed parallel to at least a portion of the front plate and/or the rear plate.

11. The electronic device of claim 10, wherein the conductive pattern is an antenna for wireless charging including a plurality of turns substantially parallel to one surface of the rear plate and/or the front plate.

12. The electronic device of claim 1, further comprising a first elastic member disposed between the rear plate and the conductive pattern portion to absorb an impact applied to the conductive pattern portion.

13. The electronic device of claim 1, further comprising a second elastic member disposed between the rear plate and the antenna to absorb an impact applied to the antenna.

14. The electronic device of claim 1, further comprising:

a main circuit board disposed between the supporting member and the front plate, in the housing; and

an electric component disposed on the main circuit board and disposed to at least partially overlap at least a portion of the antenna,

wherein the third area of the supporting member includes an opened structure, and wherein at least a portion of the heat dissipation member is disposed to pass through the opened structure.

15. The electronic device of claim 14, wherein a first heat dissipation portion of the heat dissipation member is disposed on one surface facing in a first direction of the supporting member, in the first area, and a second heat dissipation portion of the heat dissipation member is disposed on one surface facing in a second direction, opposite to the first direction of the supporting member, in the second area to be disposed adjacent to the electric component.

16. An electronic device comprising:

a housing including a plate;

a supporting member disposed in the housing and including a first area, a second area spaced apart from the first area, and a third area connecting the first area and the second area;

a conductive pattern portion disposed over the first area of the supporting member and configured to generate a magnetic field;

an antenna disposed over the second area of the supporting member and including a circuit board and a patch-type conductive portion disposed on one surface of the circuit board; and

a heat dissipation member including a first heat dissipation portion disposed under the conductive pattern portion, a second heat dissipation portion disposed under the antenna, and a third heat dissipation portion connecting the first heat dissipation portion and the second heat dissipation portion and positioned along the third area.

17. The electronic device of claim 16, wherein the second heat dissipation portion of the heat dissipation member is configured as a ground surface of the antenna.

18. The electronic device of claim 16, wherein the third heat dissipation portion includes:

a 3-1th heat dissipation portion formed of the same material as the first heat dissipation portion; and

a 3-2th heat dissipation portion formed of the same material as the second heat dissipation portion and different from the first heat dissipation portion.

19. The electronic device of claim 18, further comprising a conductive adhesive disposed between the 3-1th heat dissipation portion and the 3-2th heat dissipation portion of the heat dissipation member to adhere the 3-1th heat dissipation portion and the 3-2th heat dissipation portion and to provide a heat transfer path.

20. The electronic device of claim 16, further comprising:

a main circuit board disposed under the heat dissipation member, in the housing; and

an electric component disposed on the main circuit board and disposed to at least partially overlap at least a portion of the antenna,

wherein heat generated from the electric component is transferred through the second heat dissipation portion and the third heat dissipation portion to the first heat dissipation portion.